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Irish Standard
I.S. EN IEC 62769-4:2021

Field Device Integration (FDI) - Part 4: FDI Packages

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EN IEC 62769-4

March 2021

ICS 25.040.40; 35.100.05

Supersedes EN 62769-4:2015 and all of its amendments and corrigenda (if any)

English Version

Field Device Integration (FDI) - Part 4: FDI Packages (IEC 62769-4:2021)

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European foreword

The text of document 65E/761/FDIS, future edition 2 of IEC 62769-4, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-4:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2021-12-12
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IEC 62769-2	NOTE	Harmonized as EN 62769-2
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Annex ZA
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Normative references to international publications with their corresponding European publications

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IEC 61804	series	Function blocks (FB) for process control and electronic device description language (EDDL)	EN IEC 61804	series
IEC 61804-5	2015	Function blocks (FB) for process control and electronic device description language (EDDL) - Part 5: EDDL Builtin library	EN 61804-5	2015
IEC 62769-1	-	Field Device Integration (FDI) - Part 1: Overview	EN 62769-1	-
IEC 62769-6	-	Field Device Integration (FDI) - Part 6: Technology Mapping	EN 62769-6	-
ISO/IEC 29500-2	2016	Information technology - Document description and processing languages - Office Open XML File Formats - Part 2: Open Packaging Conventions	-	-
ISO 639-1	-	Codes for the representation of names of languages - Part 1: Alpha-2 code	-	-
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Intégration des appareils de terrain (FDI) – Partie 4: Paquetages FDI

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Field device integration (FDI) – Part 4: FDI Packages

Intégration des appareils de terrain (FDI) – Partie 4: Paquetages FDI

INTERNATIONAL ELECTROTECHNICAL COMMISSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

FOREWORD

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International Standard IEC 62769-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) support for Package Developers to build EDDs targeted for today's EDD bases system under a single development tool;
b) digital signature now includes trusted timestamping for long-term validation of FDI Package;
c) time stamp for device package signature.

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The text of this International Standard is based on the following documents:

FDIS	Report on voting
65E/761/FDIS	65E/771/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

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INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

– Part 1: Overview
– Part 2: FDI Client
– Part 3: FDI Server
– Part 4: FDI Packages
– Part 5: FDI Information Model
– Part 6: FDI Technology Mapping
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FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

1 Scope

This part of IEC 62769 specifies the FDI Packages. The overall FDI architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in Figure 1.

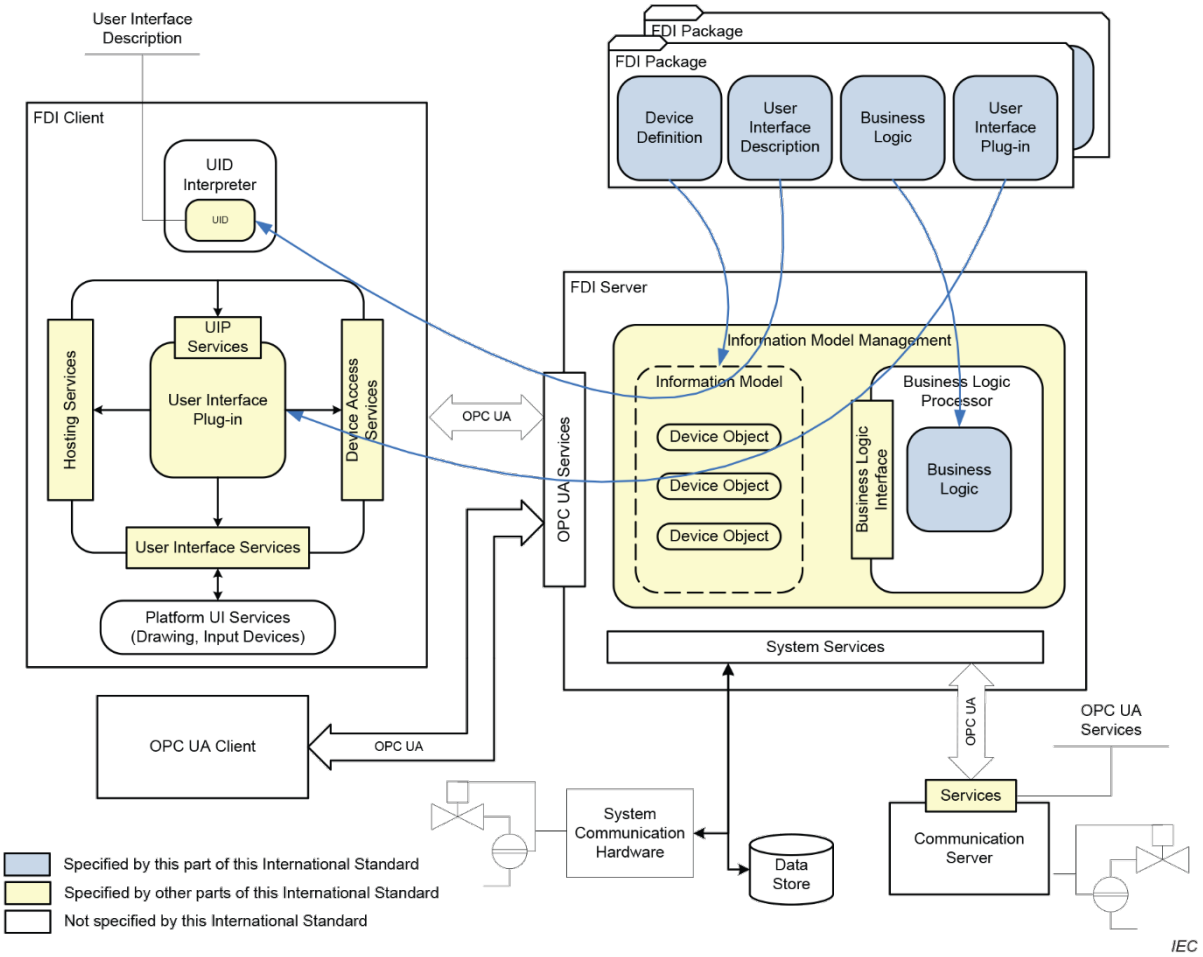

Figure 1 – FDI architecture diagram

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